EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2933	(semiconductor or die or dice or chip or IC) with (alignment or mark$3 or cod$3 or align$4) with (encapsula$4 or mold$3 or resin)	USPAT	OR	ON	2008/04/22 13:14
L2	47	(semiconductor or die or dice or chip or IC) with (alignment near mark$3) with (encapsula$4 or mold$3 or resin)	USPAT	OR	ON	2008/04/22 13:15
L3	1592	(semiconductor or die or dice or chip or IC) with (alignment or mark$3) with (encapsula$4 or mold$3 or resin)	USPAT	OR	ON	2008/04/22 13:21
L4	26	(semiconductor or die or dice or chip or IC) with (alignment or mark$3) with covered with (encapsula$4 or mold$3 or resin)	USPAT	OR	ON	2008/04/22 13:27
L5	29	(semiconductor or die or dice or chip or IC) with (alignment or mark$3) with covered with (encapsula$4 or mold$3 or resin or transparent$3 or translus$4)	USPAT	OR	ON	2008/04/22 13:28
L6	39	("3751587" | "4148057" | "4375025" | "4585931" | "4638144" | "4707722" | "4719502" | "4753863" | "4861620" | "4945204" | "4964948" | "5030551" | "5157412" | "5206280" | "5262470" | "5268194" | "5302553" | "5329090" | "5346802" | "5348033" | "5357077" | "5373039" | "5413629" | "5445923" | "5493801" | "5741361" | "5761803" | "5817541" | "5822856" | "5887345").PN. OR ("6121067").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/22 13:32
L7	18	("4125418" | "5128283" | "5270255" | "5456756").PN. OR ("5738961").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/22 13:34
L8	49	(semiconductor or die or dice or chip or IC) with (alignment or mark$3 or cod$3 or align$4) with covered with (encapsula$4 or mold$3 or resin)	USPAT	OR	ON	2008/04/22 13:42
L9	64	(semiconductor or die or dice or chip or IC) with (alignment or mark$3 or cod$3 or align$4) with covered with (encapsula$4 or mold$3 or resin or transparent$3 or translus$4)	USPAT	OR	ON	2008/04/22 13:42

L10	854	(semiconductor or die or dice or chip or IC) with (alignment or mark$3 or cod$3 or align$4) with formed with (encapsula$4 or mold$3 or resin or transparent$3 or translus$4)	USPAT	OR	ON	2008/04/22 13:49
L11	0	(semiconductor or die or dice or chip or IC) with (alignment or mark$3 or cod$3 or align$4) with encapsulted with (encapsula$4 or mold$3 or resin or transparent$3 or translus$4)	USPAT	OR	ON	2008/04/22 13:50
L12	823	10 not 9	USPAT	OR	ON	2008/04/22 13:50
L13	4	("6121067" | "6143587").PN. OR ("6680220").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/22 13:59
L14	16	("3795845" | "4732646" | "5198963" | "5283468" | "5405810" | "5422435" | "5434453" | "5508565" | "5572068" | "5894172" | "6133637" | "6278193").PN. OR ("6476499").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/22 14:06
L15	15	("4027246" | "4095095" | "4419747" | "4825093" | "4962423" | "5175774" | "5463459" | "5475268" | "5557411" | "5560775" | "5651798").PN. OR ("5894172").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/04/22 14:29
L16	1245	3 not 10	USPAT	OR	ON	2008/04/22 14:34